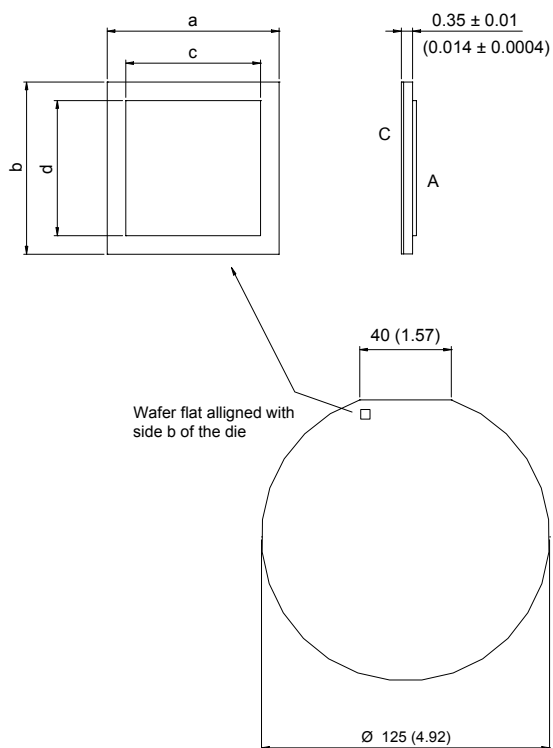


International  
**IOR** Rectifier

**FD120H06A5BT**

Fred Die in Wafer Form



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
2. CONTROLLING DIMENSION (INCH):
3. DIMENSIONS AND TOLERANCES:
  - $a = 3.048 \pm 0.05$   
( $0.120 \pm 0.002$ )
  - $b = 3.048 \pm 0.05$   
( $0.120 \pm 0.002$ )
  - $c = 2.388 \pm 0.003$   
( $0.094 \pm 0.0001$ )
  - $d = 2.388 \pm 0.003$   
( $0.094 \pm 0.0001$ )
4. LETTER DESIGNATION:
  - A = Anode (Top Metal)
  - C = Cathode (Back Metal)
5. SAWING:
  - Recommended Blade
  - SEMITEC S1025 QS00 Blade
6. MINIMUM ORDER QUANTITY:
  - 900 die

NOT TO SCALE

Reference IR Packaged Part: 15ETH06 Series

FD120H06A5BT  
Preliminary Data Sheet PD-20183 01/01

International  
**IR** Rectifier

### Electrical Characteristics (Wafer Form)

Parameters	Units	Test Conditions
$V_{FM}$ Maximum Forward Voltage	2.3 V	$T_J = 25^\circ\text{C}$ , $I_F = 15\text{ A}$
$V_{RRM}$ Minimum Reverse Breakdown Voltage	600 V	$T_J = 25^\circ\text{C}$ , $I_{RRM} = 200\ \mu\text{A}$
$I_{RM}$ Max. Reverse Leakage Current	100 $\mu\text{A}$	$T_J = 25^\circ\text{C}$ , $V_{RRM} = 600\text{ V}$
$t_{rr}$ Typ. Reverse Recovery Time	20 ns	$I_F = 1\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$

### Mechanical Data

Nominal Back Metal Composition, Thickness	Cr - Ni - Ag (1 KA - 2 KA - 3 KA)
Nominal Front Metal Composition, Thickness	99% Al, 1% Si (3 microns)
Chip Dimensions	0.120" x 0.120" (see drawing)
Reject Ink Dot Size	0.25 mm diameter minimum
Recommended Storage Environment	Storage in original container, in dessicated nitrogen, with no contamination

### Ordering Information Table

Device Code		<b>FD</b>	<b>120</b>	<b>H</b>	<b>06</b>	<b>A</b>	<b>5</b>	<b>B</b>
		①	②	③	④	⑤	⑥	⑦
<b>1</b>	- Fred Die							
<b>2</b>	- Chip Dimension in Mils:	120	=	120x120 square				
<b>3</b>	- Process	H	=	HyperFast				
<b>4</b>	- Voltage code $V_{rrm}$ (*100) eg:	06	=	600V				
<b>5</b>	- Chip surface metallization:	A	=	Aluminium (anode), Silver (cathode)				
<b>6</b>	- Wafer diameter in inches							
<b>7</b>	- Packaging:	B	=	Inked Probed Unsawn Wafer (Wafer in box)				